

Global Solder Ball Market Data Survey Report 2025

<https://marketpublishers.com/r/GC6352C1332EN.html>

Date: November 2017

Pages: 81

Price: US\$ 1,500.00 (Single User License)

ID: GC6352C1332EN

Abstracts

SUMMARY

In integrated circuit packaging, a solder ball, also a solder bump (often referred to simply as 'ball' or 'bumps') is a ball of solder that provides the contact between the chip package and the printed circuit board, as well as between stacked packages in multichip modules. The Solder Ball can be placed manually or by automated equipment, and are held in place with a tacky flux.

The global Solder Ball market will reach Volume Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

Senju Metal

DS HiMetal

MKE

YCTC

Nippon Micrometal

Accurus

PMTC

Shanghai hiking solder material

Shenmao Technology

Major applications as follows:

BGA

CSP & WLCSP

Flip-Chip & Others

Regional market size, production data and export & import:

Asia-Pacific

North America

Europe

South America

Middle East & Africa

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